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(54) Title: COMPOSITION AND METHOD FOR PLANARIZING SURFACES

(57) Abstract: A composition and a method for planarizing or polishing a surface with the composition are provided. The composition comprises about 5-90 wt.% of fumed metal oxide and about 10-95 wt.% of abrasive particles, wherein about 90 % or more of the abrasive particles (by number) have a particle size no greater than 100 nm. The composition of the present invention is useful in planarizing or polishing a surface with high polishing efficiency, uniformity, and removal rate, with minimal defectivity, such as field loss of underlying structures and topography.